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applying energy to a portion of the substrate member to separate the first optical device from the second optical device.

2. The method of claim 1 wherein the energy comprises a mechanical force.

3. The method of claim 1 wherein the substrate member has an initial thickness, the first scribe line has a first depth of about 20 to 25% of the initial thickness; and the second scribe line has a second depth of about 20 to 25% of the initial thickness.

4. The method of claim 1 wherein the first optical device has a first length, a first width, and an initial thickness greater than one of the first width or the first length.

5. The method of claim 4 wherein the initial thickness is greater than each of the first width or the first length.

6. The method of claim 1 wherein the initial thickness is from about 100 microns to about 500 microns.

7. The method of claim 1 wherein each of the optical devices includes a roughened edge surface.

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8. The method of claim 1 wherein the scribe device is selected from a diamond scribe, a laser scribe, saw, chemical scribe, or dry etch scribe.

9. The method of claim 1 wherein the first scribe region is patterned.

10. The method of claim 1 wherein the first scribe region is continuous.

11. The method of claim 1 wherein the second scribe region is patterned.

12. The method of claim 1 wherein the second scribe region is continuous.

13. The method of claim 1 wherein the first scribe region and the second scribe region are offset.

14. The method of claim 1 wherein the first scribe is provided in a region overlying the second scribe.

15. A method as in claim 1 wherein the optical devices comprise light emitting diodes and the individual die comprises a single light emitting diode.

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